# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
ANDREAS TONDER	09/17/2015
MARTIN HEIDEL	09/17/2015
EDWARD-ROBERT TYERCHA	09/17/2015
JUCHANG LEE	09/17/2015

## **RECEIVING PARTY DATA**

Name:	SAP SE
Street Address:	SAP GLOBAL IP GROUP
Internal Address:	SAP SE, DIETMAR-HOPP-ALLEE 16
City:	WALLDORF
State/Country:	GERMANY
Postal Code:	D-69190

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14861438

### CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 1933.3220000

NAME OF SUBMITTER: HARISH RUCHANDANI

SIGNATURE: /Harish Ruchandani, Reg. No. 58,770/

DATE SIGNED: 09/22/2015

**Total Attachments: 4** 

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PATENT REEL: 036626 FRAME: 0121

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> PATENT REEL: 036626 FRAME: 0122

SAP Ref. No.: 150563US01 SKGF Ref. No.: 1933,3220000

### ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the undersigned inventors: Andreas Tonder, Martin Heidel, Edward-Robert Tyercha and Juchang Lee, hereby sell and assign to SAP SE, a corporation formed under the laws of Germany, whose mailing address is SAP Global IP Group, SAP SE, Dietmar-Hopp-Allee 16, Walldorf, Germany D-69190 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above in part (a), to the full extent of the term or terms for which Letters Patents issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

PATENT REEL: 036626 FRAME: 0123

SAP Ref. No.: 150563US01 SKGF Ref. No.: 1933.3220000

The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with CUSTOMER NUMBER 82515 the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned inventors hereby represent that he/she understands that the patent practitioners associated with CUSTOMER NUMBER 82515 are the legal representatives of, and attorneys for, the assignee, and are <u>NOT</u> the legal representatives of, and attorneys for, the inventors.

his/ber		executed by the undersig	gned inventors on the date opposite
Date:_	2015/09/17	Signature of Inventor: _	1-52
			Andreas Tonder
Date:_	17. 9. 15	Signature of Inventor:	Martin Heidel
Date:	2345/43/17	Signature of Inventor.	TACLE
		<del>-</del>	Edward-Robert Tyercha
Date:_		Signature of Inventor: _	Suchana Las

SAP Ref. No.: 150563US01 SKGF Ref. No.: 1933.3220000

#### ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the undersigned inventors: Andreas Tonder, Martin Heidel, Edward-Robert Tyercha and Juchang Lee, hereby sell and assign to SAP SE, a corporation formed under the laws of Germany, whose mailing address is SAP Global IP Group, SAP SE, Dietmar-Hopp-Allee 16, Walldorf, Germany D-69190 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above in part (a), to the full extent of the term or terms for which Letters Patents issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignce, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

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The undersigned inventors hereby represent that he/she understands that the patent practitioners associated with CUSTOMER NUMBER 82515 are the legal representatives of, and attorneys for, the assignee, and are <u>NOT</u> the legal representatives of, and attorneys for, the inventors.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date:	Signature of Inventor:	(KK)
	Andreas Tonder	
Date:	Signature of Inventor:	
.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Martin Heidel	
Date:	Signature of Inventor:	
	Edward-Robert Tyercha	
Date: 17/40p/2015	Signature of Inventor:	***
	Judiang Lee	

Page 2 of 2